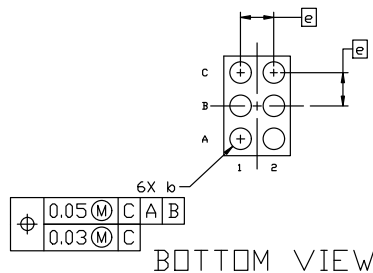
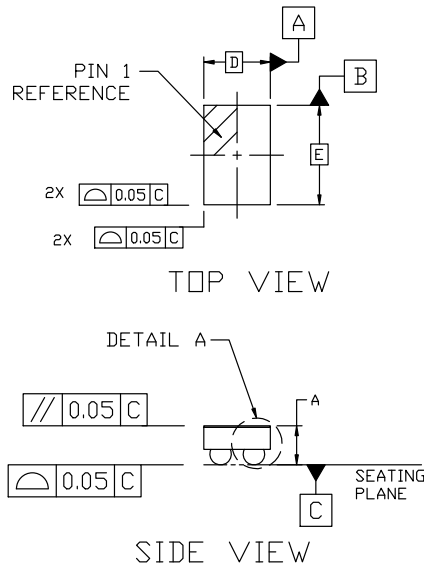
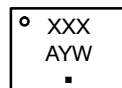

WLCSP6, 1.00x1.50x0.592
CASE 568AN
ISSUE C

DATE 28 JUN 2022


GENERIC
MARKING DIAGRAM*


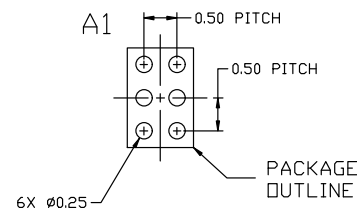
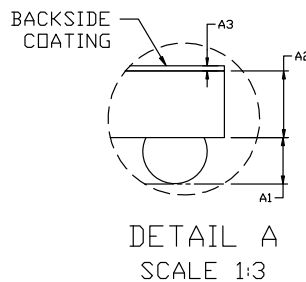
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.542	0.592	0.642
A1	0.207	0.232	0.257
A2	0.310	0.335	0.360
A3	0.025 BSC		
b	0.298	0.323	0.348
D	1.00 BSC		
E	1.50 BSC		
e	0.50 BSC		



RECOMMENDED
MOUNTING FOOTPRINT*
* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP6, 1.00X1.50X0.592	PAGE 1 OF 1

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